

AZ nLOF 2070 – run sheet

Merck

[nanyte.com/photoresists/az-nlof-2070](https://www.merck.com/photonics/photoresists/az-nlof-2070) · last updated 2026-07-26

Thickness: 5.3–11.8 μm

Softbake: 110 °C (100–110 °C) · 1.5 min · hotplate

Post-exposure bake: 110 °C (100–115 °C) · 1.5 min

Develop: Developer AZ 300MIF · Dilution undiluted (ready-to-use 0.26N / 2.38% TMAH developer; no dilution ratio stated) · Time 2 min · Method puddle